

L Number	Hits	S arch T xt	DB	Tim stamp
1	514	(228/122.1).CCLS.	USPAT; US-P PUB; EP ; JPO; DERWENT; IBM_TDB	2003/03/03 10:43
8	16467	(ceramic\$5 alumina (aluminum adj oxide) (aluminum adj nitride) molybdenum) same metal\$5 same (solder\$4 braz\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 10:53
15	166	((228/122.1).CCLS.) and ((ceramic\$5 alumina (aluminum adj oxide) (aluminum adj nitride) molybdenum) same metal\$5 same (solder\$4 braz\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 10:56
22	7824	(ceramic\$5 alumina (aluminum adj oxide) (aluminum adj nitride) molybdenum) same metal\$5 same (solder\$4 braz\$4) same (bond\$5 join\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 10:56
29	143	((228/122.1).CCLS.) and ((ceramic\$5 alumina (aluminum adj oxide) (aluminum adj nitride) molybdenum) same metal\$5 same (solder\$4 braz\$4) same (bond\$5 join\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 12:11
36	12	"4932582"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 11:21
43	5	((228/122.1).CCLS.) and (fine near2 (powder particle material)) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 12:16
57	5	(("4050956") or ("3600144") or ("4580714") or ("4582240") or ("4621761")).PN.	USPAT	2003/03/03 12:25
50	31	((228/122.1).CCLS.) and ((thermal near2 stress\$4) same (ceramic cermet (low adj expan\$6)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:03
59	34	((228/122.1).CCLS.) and (((ceramic alumina cermet) near3 layer\$5) same ((braz\$5 solder\$5) near3 layer\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 12:39
66	136	(ch i with li).in. (ryusuke with ushikoshi).in. (hid yoshi with tsuruta).in. (tomoyuki with fujii).in.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:12

73	0	(ch i with li).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:13
80	78	(ch u with li).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:30
87	2	("6057513").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:33
94	4	"6348273"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 13:58
101	294	ceramic with fine with particles with (plat\$4 sputter\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 14:01
108	109	ceramic with fine with particles with (plat\$4 sputter\$4) with metal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/03 14:02
-	10	(takahiro with ishikawa).in.	US-PGPUB	2003/02/28 14:52
-	10	platy with solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/21 16:14
-	1	"4932582".PN.	USPAT; US-PGPUB	2003/02/21 16:13
-	1	"6057513".PN.	USPAT; US-PGPUB	2003/02/27 11:59
-	180000	ceramic same metal\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/21 16:16
-	20327	ceramic same solder\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/21 16:16

-	7302	(c ramic sam metal\$4) and (c ramic sam s ld r\$4) and lay r\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/21 16:17
-	2	("6348273").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:02
-	4958	((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:04
-	182756	(428/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:11
-	60102	(148/\$).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:12
-	242867	((((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253)).CCLS.) ((428/\$).ccls.) ((148/\$).ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:12
-	18	(aluminum adj nitride) and (metallic adj molybdenum) and alumina	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:15
-	6	(((((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253)).CCLS.) ((428/\$).ccls.) ((148/\$).ccls.)) and ((aluminum adj nitride) and (m tallic adj m lybdenum) and alumina)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:32

-	29	comp sit and d nt\$5 and protrud\$5 and s ld r and c ramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:37
-	932	ceramic\$5 with m tal\$6 with bond\$6 with solder\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:39
-	35080	solder with (au gold ag silver cu copper pd palladium al aluminum ni nickel)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:41
-	432	(ceramic\$5 with metal\$6 with bond\$6 with solder\$5) and (solder with (au gold ag silver cu copper pd palladium al aluminum ni nickel))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:42
-	90	((((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253)).CCLS.) ((428/\$).ccls.) ((148/\$).ccls.)) and ((ceramic\$5 with metal\$6 with bond\$6 with solder\$5) and (solder with (au gold ag silver cu copper pd palladium al aluminum ni nickel)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/27 12:42
-	2	((("6057513") or ("4932582"))).PN.	USPAT	2003/02/28 14:57
-	11696	bond\$5 with ceramic with metal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:10
-	347	(fine near2 particle) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:03
-	13	(bond\$5 with ceramic with metal\$5) and ((fine near2 particle) same solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:11

-	7251	((228/120) or (228/121) r (228/122.1) r (228/175) or (228/176) r (228/178) r (228/188) or (228/189) r (228/190) or (228/225) r (228/226) r (228/228) or (228/234.1) r (228/245) r (228/246) or (228/248.1) or (228/248.5) or (228/249) r (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:06
-	300	(bond\$5 with ceramic with metal\$5) and (((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:06
-	155	((bond\$5 with ceramic with metal\$5) and (((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.)) and solder\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:06
-	26	((fine near2 particle) same solder) and (((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:06
-	16	((fine near2 particle) same solder) and (((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.)) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:06

-	167	(((b nd\$5 with ceramic with metal\$5) and (((228/120) r (228/121) r (228/122.1) r (228/175) r (228/176) or (228/178) r (228/188) r (228/189) or (228/190) or (228/225) r (228/226) r (228/228) r (228/234.1) r (228/245) or (228/246) r (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.)) and solder\$5) (((fine near2 particle) same solder) and (((228/120) or (228/121) or (228/122.1) or (228/175) or (228/176) or (228/178) or (228/188) or (228/189) or (228/190) or (228/225) or (228/226) or (228/228) or (228/234.1) or (228/245) or (228/246) or (228/248.1) or (228/248.5) or (228/249) or (228/250) or (228/251) or (228/253) or (174/260) or (29/843) or (428/621)).CCLS.)) and ceramic)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:07
-	4442	solder\$5 with ceramic with metal\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:11
-	24	(solder\$5 with ceramic with metal\$5) and ((fine near2 particle) same solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:19
-	3904	(fine near particles) same (ceramic cermet)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:22
-	694	(fine near particles) same (ceramic cermet) same coat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:24
-	31	((fine near particles) same (ceramic cermet)) and (solder\$5 with ceramic with metal\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:24
-	3	((fine near particles) same (ceramic cermet) same coat\$4) and (solder\$5 with ceramic with metal\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:24
-	31	(((fin near particl s) sam (c ramic c rm t)) and (sold r\$5 with c ramic with m tal\$5)) (((fin n ar particl s) sam (c ramic c rm t) sam coat\$4) and (s ld r\$5 with ceramic with m tal\$5))	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/28 15:24